



Highly heat resistant Low CTE Multi-layer circuit board materials <High-Tg type>

高耐熱・低熱膨張多層基板材料 <High-Tgタイプ>



Laminate **R-1755V**

Prepreg **R-1650V**

Applications 用途

ICT infrastructure equipment, Measuring instrument, Etc.

ICT インフラ機器、計測機器など



Good for hybrid board with MEGTRON series. Standard loss material.

スタンダード領域の伝送ロスを有しており、MEGTRON シリーズとのハイブリットが可能

Dk 4.4 Df 0.016
@1GHz

Tg (DSC)
173°C

T288 (with copper)
20min

■ IST (Interconnect Stress Test)

● Result

Sample No.	Reflow condition	HiPER V R-1755V
1	—	Over 1000 cycles OK
2	230°C x 3times	Over 1000 cycles OK
3	230°C x 6times	Over 1000 cycles OK
4	260°C x 3times	Over 1000 cycles OK
5	260°C x 6times	Over 1000 cycles OK

● Condition

Pretreatment	Reflow
	25°C (2min) ⇔ 150°C (3min)

* Failure is over 10% changes of resistance

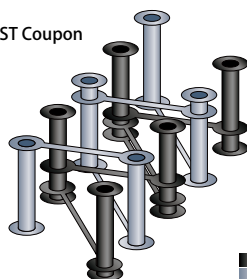
● Construction

Board thickness	2.1mm
Number of layers	18 layers

What is IST ?

Carrying out temperature cycling experiments 25°C ⇔ 150°C by electric heating to the power unit. By detecting the occurrence of deficiencies in the sense unit, evaluating the number of cycles to failure occurrences.

IST Coupon



Power Sense

■ Solder heat resistance (float) はんだフロート耐熱性

● Result

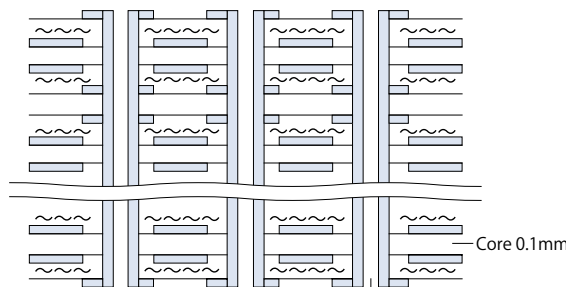
R-1755V : No abnormality of cross-sectional observation

● Condition

288°C 10sec. Solder float 6 cycles

● Construction

Board thickness	3.1mm
Layer count	24 layers
Drill diameter/Pitch	0.25 mm φ / 0.76mm



Prepreg #2116 53% 1ply

■ General properties 一般特性

Item	Test method	Condition	Unit	HiPER V R-1755V	
Glass transition temp.(Tg)	DSC	A	°C	173	
CTE z-axis	IPC-TM-650 2.4.24	A	ppm/°C	α 1	
				α 2	
T288 (with copper)	IPC-TM-650 2.4.24.1	A	min	20	
Dielectric constant (Dk)	1GHz	IPC-TM-650 2.5.5.9	C-24/23/50	—	
Dissipation factor (Df)					0.016
Peel strength	1oz(35 μm)	IPC-TM-650 2.4.8	A	kN/m	1.5

The sample thickness is 0.8mm.

The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。

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